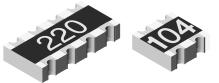
Thick Film Resistor Array



CRA06P Thick Film resistor array is constructed on a high grade ceramic body with concave terminations. A small package enables the design of high density circuits. The single component reduces board space, component counts and assembly costs.

FEATURES

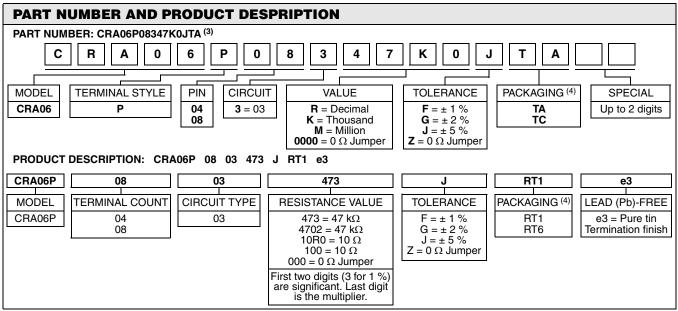
- Concave terminal array with square corners
- 4 and 8 terminal package with isolated resistors
- Wide ohmic range: 10R to 1M0
- Lead (Pb)-free solder contacts on Ni barrier layer
- Pure tin plating provides compatibility with lead (Pb)-free and lead containing soldering processes
- Compatible with "Restriction of the use of Hazardous Substances" (RoHS) directive 2002/95/EC (issue 2004)

STANDARD ELECTRICAL SPECIFICATIONS									
MODEL	CIRCUIT	POWER RATING P _{70 °C} W	LIMITING ELEMENT VOLTAGE MAX. V≅	TEMPERATURE COEFFICIENT ppm/K	TOLERANCE %	RESISTANCE RANGE Ω	E-SERIES		
CRA06P	03	0.063	50	± 100 ± 200	± 1 ± 2; ± 5	10R - 1M0	24 + 96 24		
		Zero-Ohm-Resistor: $R_{max.} = 50 \text{ m}\Omega$, $I_{max.} = 1 \text{ A}$							

TECHNICAL SPECIFICATIONS					
PARAMETER	UNIT	CRA06P 03 CIRCUIT			
Rated Dissipation at 70 °C ⁽²⁾	W per element	0.063			
Limiting Element Voltage (1)	V≅	50			
Insulation Voltage (1 min)	V _{dc/ac peak}	100			
Category Temperature Range	°C	- 55 to + 125 (+ 155)			
Insulation Resistance	Ω	> 10 ⁹			

Notes:

(2) The power dissipation on the resistor generates a temperature rise against the local ambient, depending on the heat flow support of the printed-circuit board (thermal resistance). The rated dissipation applies only if the permitted film temperature of 155 °C is not exceeded.



Notes:

(3) Preferred way for ordering products is by use of the PART NUMBER

⁽⁴⁾ Please refer to the table PACKAGING, see next page



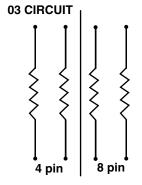
⁽¹⁾ Rated voltage: $\sqrt{P \times R}$

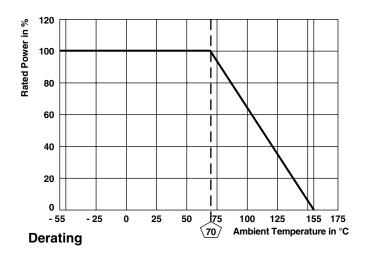


CRA06P

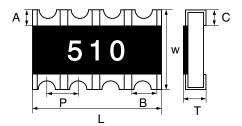
PACKAGING							
		DIAMETER	РІТСН	PIECES /REEL	PACKAGING CODE PAPER TAPE		
MODEL	TAPE WIDTH						
					PART NUMBER	PRODUCT DESCRIPTION	
CRA06P	8 mm	180 mm/7"	4 mm	5000	ТА	RT1	
CRAUOP		330 mm/13"	4 mm	20 000	TC	RT6	

CIRCUIT

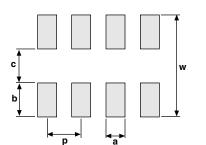




DIMENSIONS



PIN	DIMENSIONS [in millimeters]								
NO#	L	Α	В	С	Р	Т	w		
4	1.60	0.30	0.40	0.40	0.80	0.60	1.60		
8	3.20	0.30	0.40	0.40	0.80	0.60	1.60		
Tol.	± 0.20	± 0.20	± 0.15	± 0.20	-	± 0.10	± 0.15		



SOLDER PAD DIMENSIONS [in millimeters]						
	с	w	р	а	b	
WAVE	0.8	2.6	0.8	0.4	0.9	



TEST PROCEDURES AND REQUIREMENTS						
EN 60115-1						
TEST	CONDITIONS OF TEST	REQUIREMENTS PERMISSIBLE CHANGE (∆ <i>R/R</i>) ⁽¹⁾				
(clause)		STABILITY CLASS 1 OR BETTER	STABILITY CLASS 2 OR BETTER			
	Stability for product types: CRA06P	10 Ω to 1 M Ω	10 Ω to 1 M Ω			
Resistance (4.5)	-	±1%	± 2 %; ± 5 %			
Temperature coefficient (4.8.4.2)	20/- 55/20 °C and 20/125/20 °C	± 100 ppm/K	± 200 ppm/K			
Overload (4.13)	$U = 2.5 \times (P_{70} \times R)^{1/2} \le 2 \times U_{\text{max.}}; 0.5 \text{ s}$	± (0.25 % <i>R</i> + 0.05 Ω)	\pm (0.5 % R + 0.05 Ω)			
Solderability (4.17.5) ⁽²⁾	Aging 4 h at 155 °C, dryheat Solder bath method; 235 °C; 2 s Visual examination	Solder bath method; 235 °C; 2 s				
Resistance to soldering heat (4.18.2)	Solder bath method; (260 ± 5) °C; (10 ± 1) s	± (0.25 % <i>R</i> + 0.05 Ω)	± (0.5 % <i>R</i> + 0.05 Ω)			
Rapid change of temperature (4.19)	30 min at LCT = - 55 °C; 30 min at UCT = 125 °C; 5 cycles	± (0.25 % <i>R</i> + 0.05 Ω)	± (0.5 % <i>R</i> + 0.05 Ω)			
Damp heat, steady state (4.24)	(40 ± 2) °C; 56 days; (93 ± 3) % RH	± (1 % <i>R</i> + 0.05 Ω)	± (2 % <i>R</i> + 0.1 Ω)			
Climatic sequence (4.23)	16 h at UCT = 125 °C; 1 cycle at 55 °C; 2 h at LCT = - 55 °C; 1 h/1 kPa at 15 °C to 35 °C; 5 cycles at 55 °C $U = (P_{70} \times R)^{1/2}$ $U = U_{max.}$; whichever is less severe	± (1 % <i>R</i> + 0.05 Ω)	± (2 % R + 0.1 Ω)			
Endurance at 70 °C (4.25.1)	$U = (P_{70} \ge R)^{1/2}$ $U = U_{max.}$; whichever is less severe 1.5 h ON; 0.5 h OFF; 70 °C; 1000 h	± (1 % <i>R</i> + 0.05 Ω)	± (2 % R + 0.1 Ω)			
Extended endurance (4.25.1.8)	Duration extended to 8000 h	± (2 % <i>R</i> + 0.1 Ω)	± (4 % <i>R</i> + 0.1 Ω)			
Endurance at upper category temperature (4.25.3)	UCT = 125 °C; 1000 h	± (1 % <i>R</i> + 0.05 Ω)	± (2 % <i>R</i> + 0.1 Ω)			

Notes:

⁽¹⁾ Figures are given for a single element

(2) Solderability is specified for 2 years after production or requalification. Permitted storage time is 20 years

APPLICABLE SPECIFICATIONS

• EN 60115-1	Generic Specification
• EN 140400	Sectional Specification
• EN 140401-802	Detail Specification
• IEC 60068-2-X	Variety of environmental test procedures
• EIA 481	Packaging of SMD components



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